



PRODUCT CHANGE NOTICE

PCN 编号	PCN20190701-1	发行人:	发行日期: 2019/7/01
客户名称	ALL	联系人:	

受影响产品	商业名称	规格型号	备注
			所有 IC 产品

变更原因描述	延长产品包装保存期限
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1. 所有 IC 产品包装材料保质期及密封防潮措施 (MBB 防潮、干燥剂用量) 修改为 24 个月。
2. 包装标识变更如下, MSL3 标签上保存期限由 12 个月变更为 24 个月:

变更方法描述	 <p>Caution This bag contains MOISTURE-SENSITIVE DEVICES</p> <p>LEVEL 3</p> <p>1. Calculated shelf life in sealed bag: <u>12 months</u> at < 40°C and < 90% relative humidity (RH)</p> <p>2. Peak package body temperature: <u>260</u> °C</p> <p>3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be a) Mounted within: <u>168</u> hours of factory conditions ≤ 30°C/60% RH, or b) Stored per J-STD-033</p> <p>4. Devices require bake, before mounting, if: a) Humidity Indicator Card reads > 10% for level 2a-5a devices or > 60% for level 2 devices when read at 23±5°C b) 3a or 3b are not met</p> <p>5. If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure</p> <p>Bag Seal Date: Please see label on box.</p> <p>Note: Level and body temperature defined by IPC/JEDEC J-STD-020</p>	 <p>Caution This bag contains MOISTURE-SENSITIVE DEVICES</p> <p>LEVEL 3</p> <p>1. Calculated shelf life in sealed bag: <u>24 months</u> at < 40°C and < 90% relative humidity (RH)</p> <p>2. Peak package body temperature: <u>260</u> °C</p> <p>3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must a) Mounted within: <u>168</u> hours of factory conditions ≤ 30°C / 60% RH. OR b) Stored at < 10% RH</p> <p>4. Devices require bake, before mounting, if: a) Humidity Indicator Card is > 10% when read at 23 ± 5°C b) 3a or 3b not met</p> <p>5. If baking is required, devices may be baked for 48 hours at 125 ± 5°C Note: If device containers cannot be subjected to high temperature or shorter bake times are desired, reference IPC/JEDEC J-STD-033 for bake procedure</p> <p>Bag Seal Date: _____</p> <p>Note: Level and body temperature defined by IPC/JEDEC J-STD-020</p>
	变更前	变更后

变更生效日期或产品 Date Code 说明: 2019 年 7 月 1 日起开始加工的产品

华大半导体 MCU 事业部工程部经理签署:  

日期: 2019 年 7 月 1 日

客户: _____ 部确认意见: _____

签署: _____ 日期: _____